DISCRETE SEMICONDUCTORS

DATA SHEET

BYV42E, BYV42EB series Rectifier diodes ultrafast, rugged

Product specification

July 1998



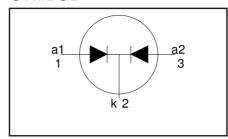
Rectifier diodes ultrafast, rugged

BYV42E, BYV42EB series

FEATURES

- · Low forward volt drop
- · Fast switching
- · Soft recovery characteristic
- Reverse surge capability
 High thermal cycling performance
- · Low thermal resistance

SYMBOL



QUICK REFERENCE DATA

$$V_R = 150 \text{ V}/ 200 \text{ V}$$

$$V_F \le 0.85 \text{ V}$$

$$I_{O(AV)} = 30 \text{ A}$$

$$I_{RRM} = 0.2 \text{ A}$$

$$t_{rr} \le 28 \text{ ns}$$

GENERAL DESCRIPTION

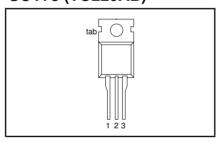
Dual, ultra-fast, epitaxial rectifier diodes intended for use as output rectifiers in high frequency switched mode power supplies.

The BYV42E series is supplied in the SOT78 conventional leaded package. The BYV42EB series is supplied in the SOT404 surface mounting package.

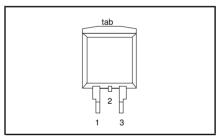
PINNING

PIN	DESCRIPTION		
1	anode 1 (a)		
2	cathode (k) 1		
3	anode 2 (a)		
tab	cathode (k)		

SOT78 (TO220AB)



SOT404



LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	I. MAX.		UNIT
		BYV42E / BYV42EB		-150	-200	
V _{RRM}	Peak repetitive reverse voltage		-	150	200	V
V _{RWM}	Crest working reverse voltage	T < 144°C	-	150	200	V
V_R	Continuous reverse voltage	T _{mb} ≤ 144°C	-	150	200	Į V
I _{O(AV)}	Average rectified output current	square wave	-	3	0	Α
` '	(both diodes conducting)	$\delta = 0.5$; $T_{mb} \le 108 ^{\circ}\text{C}$			•	١ .
I _{FRM}	Repetitive peak forward current per diode	t = 25 μs; δ = 0.5; T _{mb} ≤ 108 °C	-	3	0	Α
I _{FSM}	Non-repetitive peak forward	t = 10 ms	_	1!	50	Α
.L2M	current per diode	t = 8.3 ms	-		30	À
	· .	sinusoidal; with reapplied				
		V _{RWM(max)}				١.
I _{RRM}		$t_p = 2 \mu s; \delta = 0.001$	-	0	.2	A
l ,	per diode Non-repetitive peak reverse	t _o = 100 μs	_	ا ا	.2	A
IRSM	current per diode	μ _p = 100 μ3	_	l '		^
T _{sta}	Storage temperature		-40	1 15	50	°C
T _{stg}	Operating junction temperature		-	1 1	50	°C

1. It is not possible to make connection to pin 2 of the SOT404 package

2. SOT78 package, For output currents in excess of 20 A, the cathode connection should be made to the mounting tab.

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ESD LIMITING VALUE

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _C	ı	Human body model; C = 250 pF; R = 1.5 kΩ	-	8	kV

THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$R_{th j-mb}$ $R_{th j-a}$	mounting base	per diode both diodes SOT78 package, in free air SOT404 and SOT428 packages, pcb mounted, minimum footprint, FR4 board	1 1 1	- - 60 50	2.4 1.4 - -	K/W K/W K/W K/W

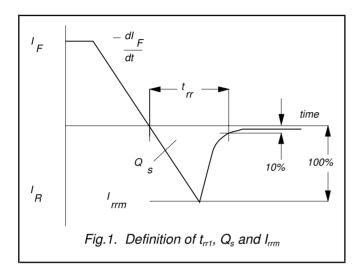
ELECTRICAL CHARACTERISTICS

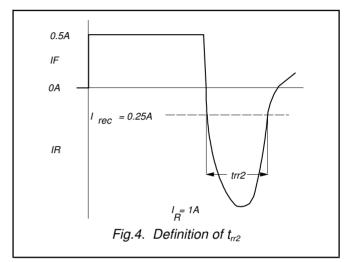
characteristics are per diode at T_i = 25 °C unless otherwise stated

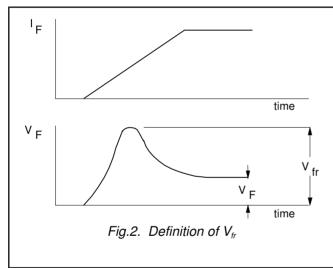
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V_{F}	Forward voltage	I _F = 15 A; T _i = 150°C	-	0.78	0.85	V
	_	$I_{\rm F} = 15 {\rm A}$	-	0.95	1.05	V
		$I_{\rm F} = 30 \text{ A}$	-	1.00	1.20	V
l _R	Reverse current	$\dot{V}_R = V_{RWM}$; $T_i = 100 ^{\circ}C$	-	0.5	1	mΑ
''		$V_{\rm R} = V_{\rm RWM}$	-	10	100	μΑ
$Q_{\rm s}$	Reverse recovery charge	$V_{R} = V_{RWM}$ $I_{F} = 2 \text{ A; } V_{R} \ge 30 \text{ V; } -dI_{F}/dt = 20 \text{ A/}\mu\text{s}$	-	6	15	'nC
t _{rr1}	Reverse recovery time	$I_{F} = 1 \text{ A}; V_{R}^{n} \ge 30 \text{ V};$	-	20	28	ns
""		I-dI₅/dt = 100 A/us				
t _{rr2}	Reverse recovery time	$I_{\rm F} = 0.5 \text{A} \text{ to } I_{\rm R} = 1 \text{A}; I_{\rm rec} = 0.25 \text{A}$	-	13	22	ns
$V_{\rm fr}$	Forward recovery voltage	$I_F = 0.5 \text{ A to } I_R = 1 \text{ A; } I_{rec} = 0.25 \text{ A}$ $I_F = 1 \text{ A; } dI_F/dt = 10 \text{ A/}\mu\text{s}$	-	1	-	V

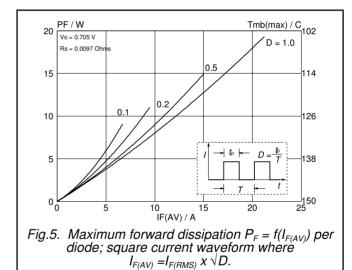
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Voltage Pulse Source

Current shunt to 'scope

Fig.3. Circuit schematic for t_{rr2}

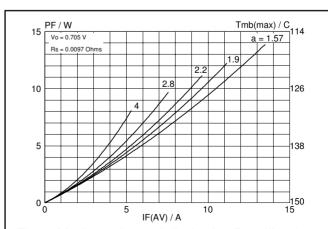
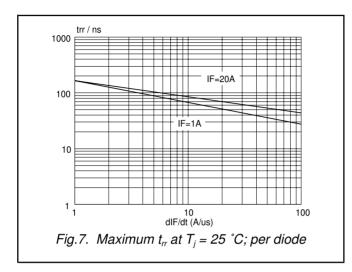
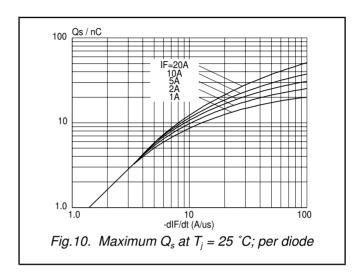


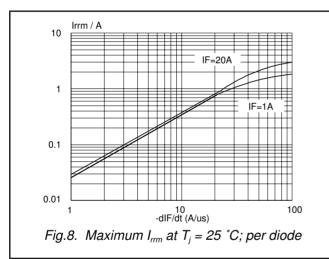
Fig.6. Maximum forward dissipation $P_F = f(I_{F(AV)})$ per diode; sinusoidal current waveform where a = form factor $= I_{F(RMS)} / I_{F(AV)}$.

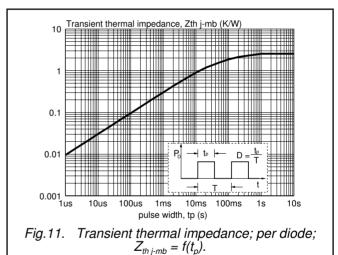
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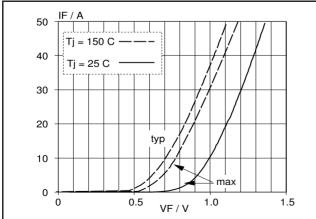
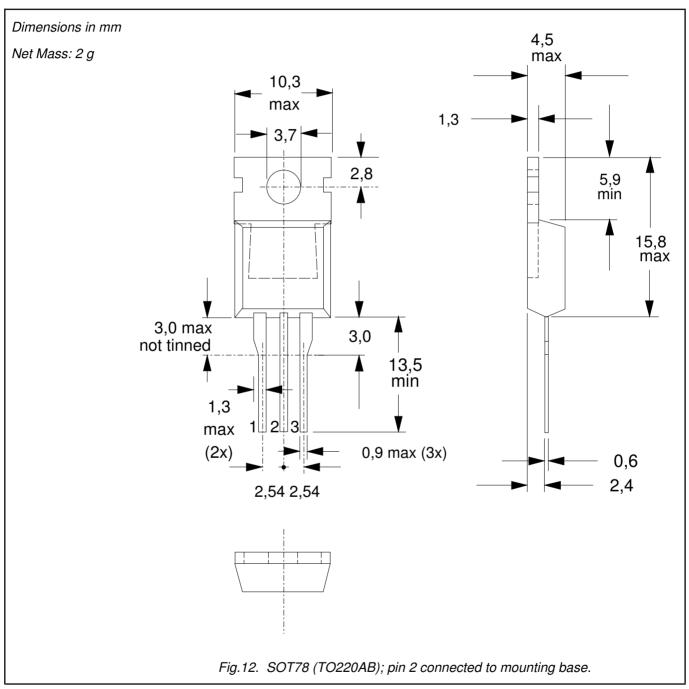


Fig.9. Typical and maximum forward characteristic $I_F = f(V_F)$; parameter T_j

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MECHANICAL DATA



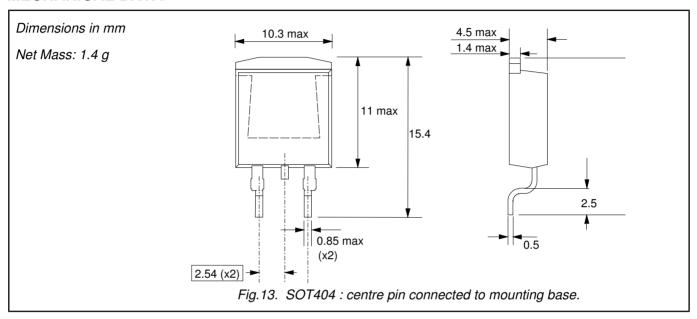
- Notes
 1. Refer to mounting instructions for SOT78 (TO220) envelopes.
 2. Epoxy meets UL94 V0 at 1/8".

NXP Semiconductors Product specification

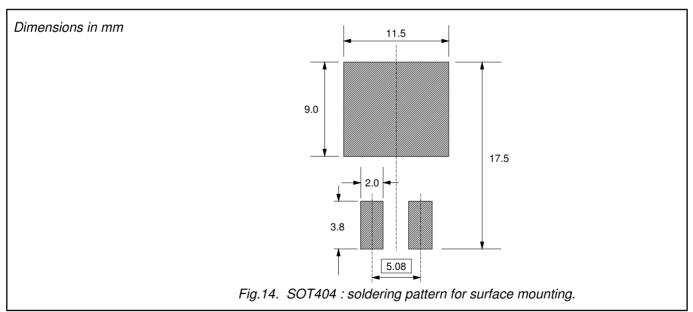
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MECHANICAL DATA



MOUNTING INSTRUCTIONS



Notes

1. Epoxy meets UL94 V0 at 1/8".

Legal information

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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